



Datasheet

S60HVV01

Including a guidance for

- PCB Footprint for single placement
- Stack-up _ FR4 1.2T 6layer

Document name	DS_S60HVV01_vB2
Date	03-Sep-2021
Version (revision)	B2
Confidential level	N/A

Overview

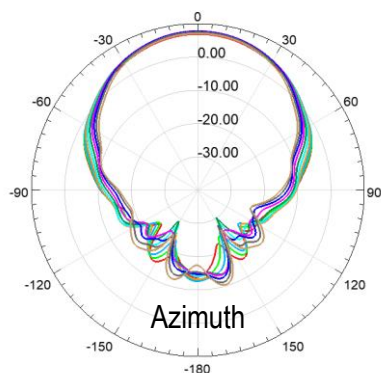
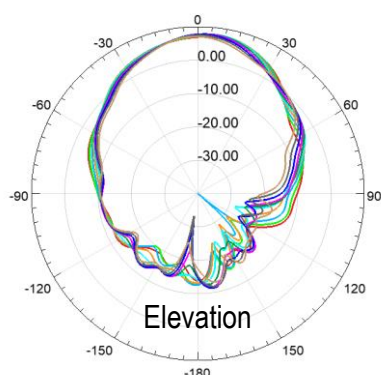
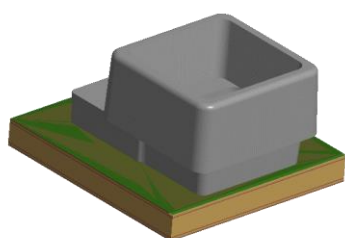
- Antenna beam radiating vertically
- Linear polarization

Specification

Frequency range [GHz]	57-66
Typical Far-Field Directivity [dBi]	≥ 8
Polarization	Linear
Return loss [dB]	≤ -10
Nominal impedance [Ω]	50

Modeling

[Horn antenna on PCB]

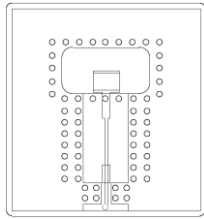


PCB information (FR4 substrate)

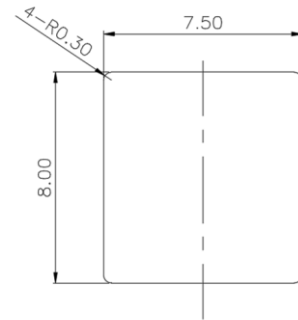
Layer	Stack Up	Spec.	Thickness (mm)	Layer
L1	Copper	HOz + 25uPL	0.04	1
	P/P	0.1T	0.10	
L2	Copper	1Oz Gu	0.035	2(GND)
	P/P	0.2T	0.2	
L3	Copper	1Oz Gu	0.035	3
	P/P	0.4T	0.4	
L4	Copper	1Oz Gu	0.035	4
	P/P	0.2T	0.2	
L5	Copper	1Oz Gu	0.035	5(Vcc)
	P/P	0.1T	0.1	
L6	Copper	HOz + 25uPL	0.04	6
Grand total thickness			1.22	

PCB layer (Single)

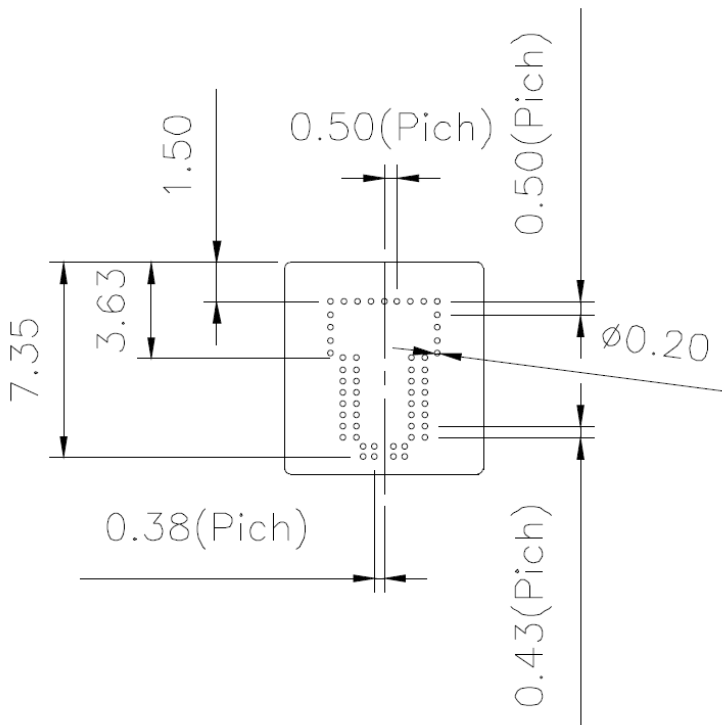
■ Layer assembly



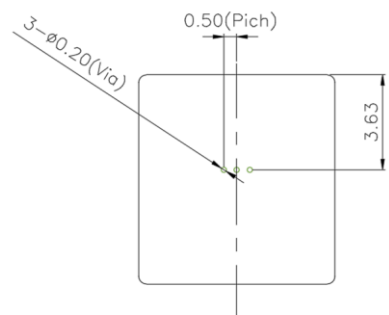
■ Contour



■ Via Hole (Layer 1 ~ Layer 6)



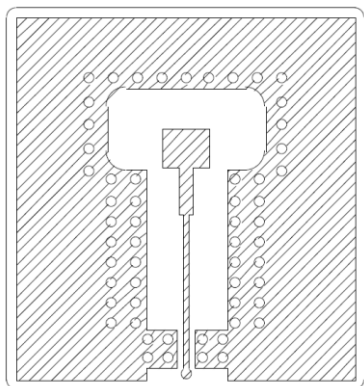
■ Via Hole (Layer 2 ~ Layer 5)



PCB layer (Single)

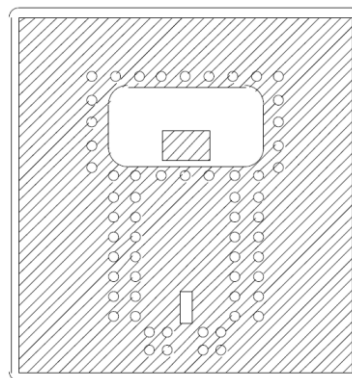
■ Copper layer 1 (Top)

 <Copper Area>



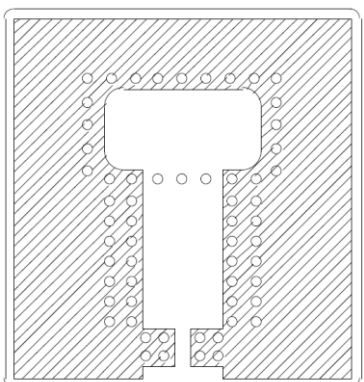
■ Copper layer 2

 <Copper Area>



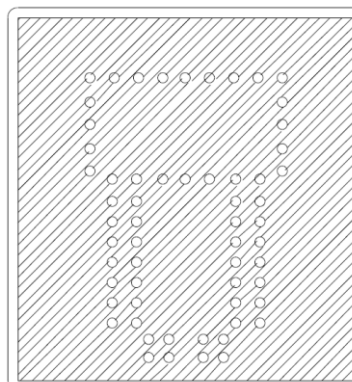
■ Copper layer 3

 <Copper Area>



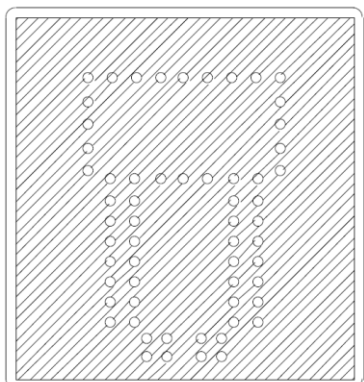
■ Copper layer 4

 <Copper Area>



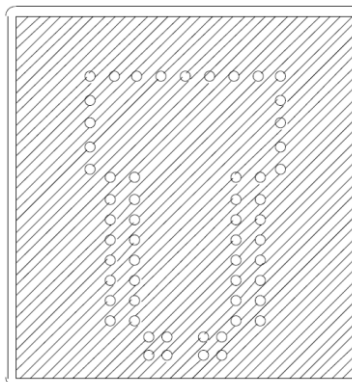
■ Copper layer 5

 <Copper Area>



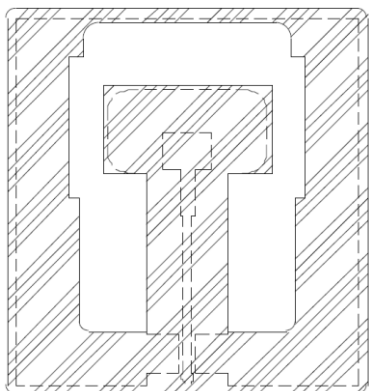
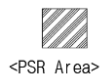
■ Copper layer 6 (Bottom)

 <Copper Area>

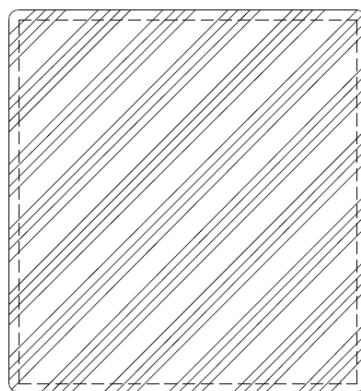
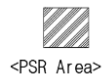


PCB layer (Single)

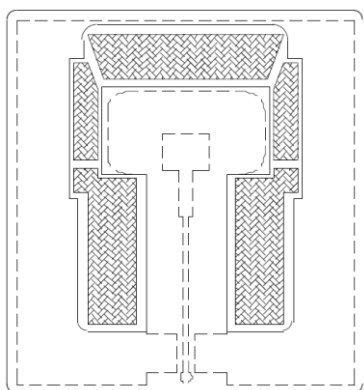
■ PSR (Top)



■ PSR (Bottom)



■ Solder paste (Top)



■ Silk screen printing (Top)

